

Single Unbuffered Inverter

MC74VHC1GU04

The MC74VHC1GU04 is an advanced high speed CMOS unbuffered inverter in tiny footprint packages.

This device consists of a single unbuffered inverter. In combination with others, or in the MC74VHCU04 Hex Unbuffered Inverter, these devices are well suited for use as oscillators, pulse shapers, and in many other applications requiring a high-input impedance amplifier. For digital applications, the MC74VHC1G04 or the MC74VHC04 are recommended.

The input structures provide protection when voltages up to 5.5 V are applied, regardless of the supply voltage. This allows the device to be used to interface 5 V circuits to 3 V circuits.

Features

- Designed for 2.0 V to 5.5 V V_{CC} Operation
- 2.5 ns t_{PD} at 5 V (typ)
- Inputs Over-Voltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection on Input
- Source/Sink 8 mA at 3.0 V
- Available in SC-88A, SC-74A, TSOP-5, SOT-553, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

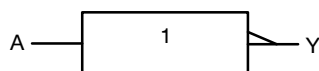


Figure 1. Logic Symbol



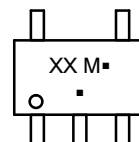
ON Semiconductor®

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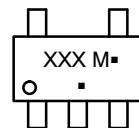
MARKING DIAGRAMS



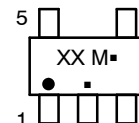
SC-88A
DF SUFFIX
CASE 419A



SC-74A
DBV SUFFIX
CASE 318BQ



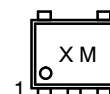
TSOP-5
DT SUFFIX
CASE 483



SOT-553
XV5 SUFFIX
CASE 463B



SOT-953
P5 SUFFIX
CASE 527AE



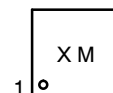
UDFN6
1.45 x 1.0
CASE 517AQ



UDFN6
1.2 x 1.0
CASE 517AA



UDFN6
1.0 x 1.0
CASE 517BX



XX = Specific Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

MC74VHC1GU04

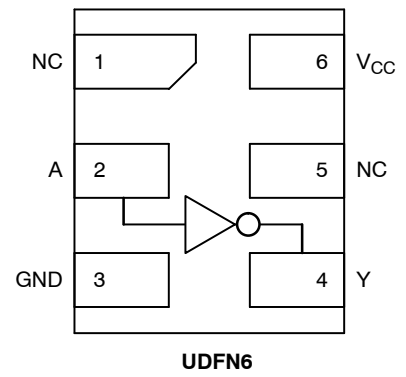
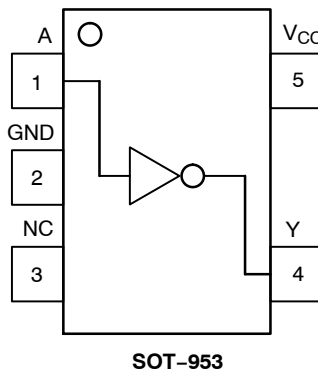
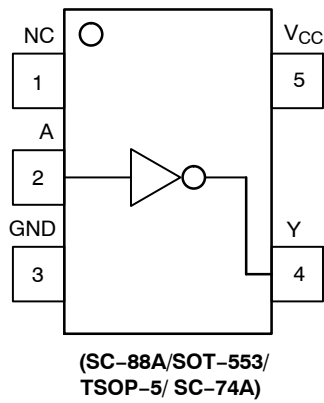


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

(SC-88A/SOT-553/ TSOP-5/SC-74A)

Pin	Function
1	NC
2	A
3	GND
4	Y
5	V _{CC}

PIN ASSIGNMENT (SOT-953)

Pin	Function
1	A
2	GND
3	NC
4	Y
5	V _{CC}

PIN ASSIGNMENT (UDFN)

Pin	Function
1	NC
2	A
3	GND
4	Y
5	NC
6	V _{CC}

FUNCTION TABLE

Input	Output
A	Y
L	H
H	L

MC74VHC1GU04

MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit
V _{CC}	DC Supply Voltage TSOP-5, SC-88A (NLV) SC-74A, SC-88A, UDFN6, SOT-553, SOT-953	-0.5 to +7.0 -0.5 to +6.5	V
V _{IN}	DC Input Voltage TSOP-5, SC-88A (NLV) SC-74A, SC-88A, UDFN6, SOT-553, SOT-953	-0.5 to +7.0 -0.5 to +6.5	V
V _{OUT}	DC Output Voltage	-0.5 to V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current	±20	mA
I _{OUT}	DC Output Source/Sink Current	±25	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin	±50	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 secs	260	°C
T _J	Junction Temperature Under Bias	+150	°C
θ _{JA}	Thermal Resistance (Note 2) SC-88A SC-74A SOT-553 SOT-953 UDFN6	377 320 324 254 154	°C/W
P _D	Power Dissipation in Still Air SC-88A SC-74A SOT-553 SOT-953 UDFN6	332 390 386 491 812	mW
MSL	Moisture Sensitivity	Level 1	-
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 3) Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)	± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

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RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	2.0	5.5	V
V _{IN}	DC Input Voltage	0	5.5	V
V _{OUT}	DC Output Voltage	0	V _{CC}	V
T _A	Operating Temperature Range	−55	+125	°C
t _r , t _f	Input Rise and Fall Time	TSOP−5, SC−88A (NLV)		ns/V
		V _{CC} = 3.0 V to 3.6 V		
		V _{CC} = 4.5 V to 5.5 V		
	Input Rise and Fall Time	SC−74A, SC−88A, UDFN6, SOT−553, SOT−953		
		V _{CC} = 2.0 V		
		V _{CC} = 2.3 V to 2.7 V		
		V _{CC} = 3.0 V to 3.6 V		
		V _{CC} = 4.5 V to 5.5 V		

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} (V)	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$		$-55^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	High-Level Input Voltage		2.0	1.7	–	–	1.7	–	1.7	–	V
			3.0	2.4	–	–	2.4	–	2.4	–	
			4.5	3.6	–	–	3.6	–	3.6	–	
			5.5	4.4	–	–	4.4	–	4.4	–	
V_{IL}	Low-Level Input Voltage		2.0	–	–	0.3	–	0.3	–	0.3	V
			3.0	–	–	0.6	–	0.6	–	0.6	
			4.5	–	–	0.9	–	0.9	–	0.9	
			5.5	–	–	1.1	–	1.1	–	1.1	
V_{OH}	High-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -50\text{ }\mu\text{A}$	2.0	1.9	2.0	–	1.9	–	1.9	–	V
			3.0	2.9	3.0	–	2.9	–	2.9	–	
			4.5	4.4	4.5	–	4.4	–	4.4	–	
		$V_{IN} = \text{GND}$ $I_{OH} = -4\text{ mA}$ $I_{OH} = -8\text{ mA}$	3.0	2.58	–	–	2.48	–	2.34	–	
			4.5	3.94	–	–	3.80	–	3.66	–	
V_{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 50\text{ }\mu\text{A}$	2.0	–	0.0	0.1	–	0.1	–	0.1	V
			3.0	–	0.0	0.1	–	0.1	–	0.1	
			4.5	–	0.0	0.1	–	0.1	–	0.1	
		$V_{IN} = V_{CC}$ $I_{OL} = 4\text{ mA}$ $I_{OL} = 8\text{ mA}$	3.0	–	–	0.36	–	0.44	–	0.52	
			4.5	–	–	0.36	–	0.44	–	0.52	
I_{IN}	Input Leakage Current	$V_{IN} = 5.5\text{ V}$ or GND	2.0 to 5.5	–	–	± 0.1	–	± 1.0	–	± 1.0	μA
I_{OFF}	Power Off Leakage Current	$V_{IN} = 5.5\text{ V}$	0	–	–	1.0	–	10	–	10	μA
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	–	–	1.0	–	20	–	40	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C			–40°C ≤ T _A ≤ 85°C		–55°C ≤ T _A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	C _L = 15 pF	3.0 to 3.6	–	3.5	8.9	–	10.5	–	12.0	ns
		C _L = 50 pF		–	4.8	11.4	–	13.0	–	15.5	
		C _L = 15 pF	4.5 to 5.5	–	2.5	5.5	–	6.5	–	8.0	
		C _L = 50 pF		–	3.8	7.0	–	8.0	–	9.5	
C _{IN}	Input Capacitance			–	4.0	10	–	10	–	10	pF

C _{PD}	Power Dissipation Capacitance (Note 5)	Typical @ 25°C, V _{CC} = 5.0 V	pF
		22.0	

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

MC74VHC1GU04

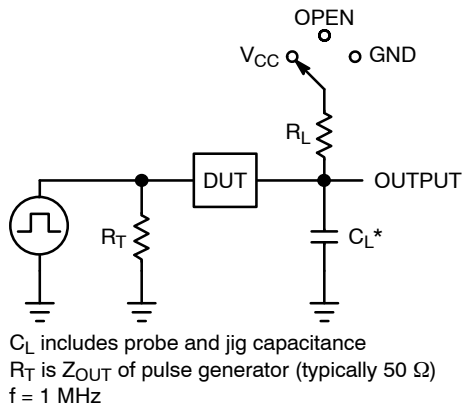


Figure 3. Test Circuit

Test	Switch Position	C_L , pF	R_L , Ω
t_{PLH} / t_{PHL}	Open	See AC Characteristics Table	X
t_{PLZ} / t_{PZL}	V_{CC}		1 k
t_{PHZ} / t_{PZH}	GND		1 k

X = Don't Care

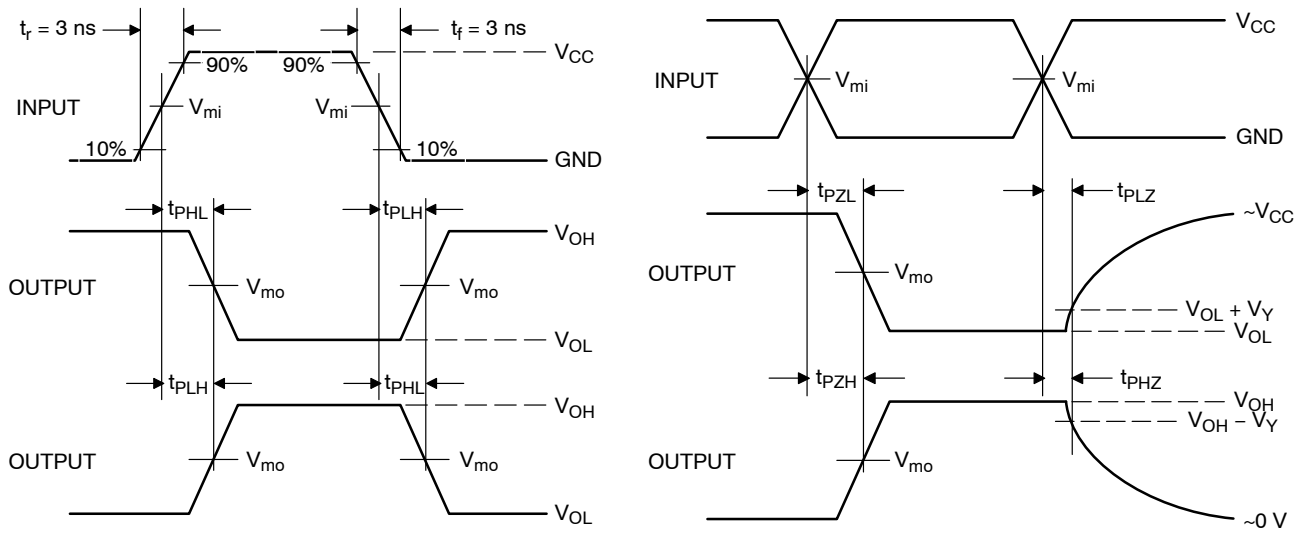


Figure 4. Switching Waveforms

V_{CC} , V	V_{mi} , V	V_{mo} , V		V_Y , V
		t_{PLH} , t_{PHL}	t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}	
3.0 to 3.6	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3
4.5 to 5.5	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3

MC74VHC1GU04

ORDERING INFORMATION

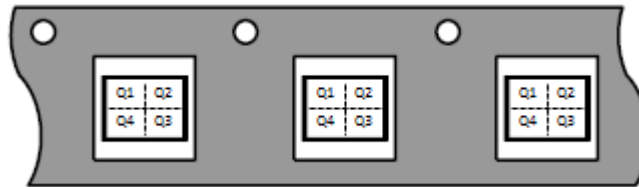
Device	Package	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
MC74VHC1GU04DF1G	SC-88A	V6	Q2	3000 / Tape & Reel
M74VHC1GU04DFT1G	SC-88A	V6	Q2	3000 / Tape & Reel
M74VHC1GU04DFT2G	SC-88A	V6	Q4	3000 / Tape & Reel
NLVVHC1GU04DFT2G*	SC-88A	V6	Q4	3000 / Tape & Reel
M74VHC1GU04DTT1G	TSOP-5	M0	Q4	3000 / Tape & Reel
MC74VHC1GU04DBVT1G	SC-74A	V6	Q4	3000 / Tape & Reel
MC74VHC1GU04MU1TCG	UDFN6, 1.45 x 1.0, 0.5P	T	Q4	3000 / Tape & Reel
MC74VHC1GU04MU2TCG (In Development)	UDFN6, 1.2 x 1.0, 0.4P	K	Q4	3000 / Tape & Reel
MC74VHC1GU04MU3TCG (In Development)	UDFN6, 1.0 x 1.0, 0.35P	Y	Q4	3000 / Tape & Reel
MC74VHC1GU04XV5T2G (In Development)	SOT-553	TBD	Q4	4000 / Tape & Reel
MC74VHC1GU04P5T5G (In Development)	SOT-953	TBD	Q2	8000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

Pin 1 Orientation in Tape and Reel

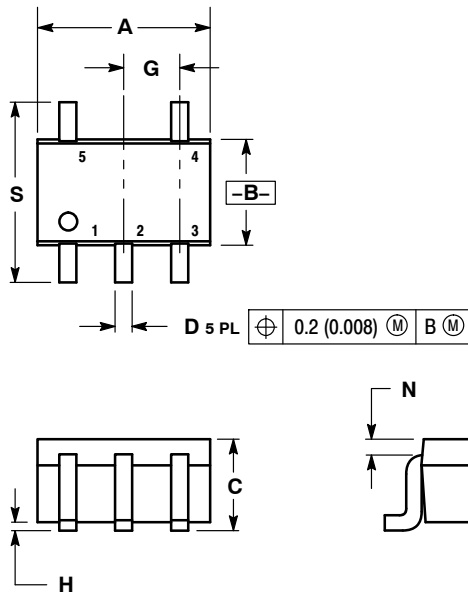
Direction of Feed



MC74VHC1GU04

PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353)
CASE 419A-02
ISSUE L

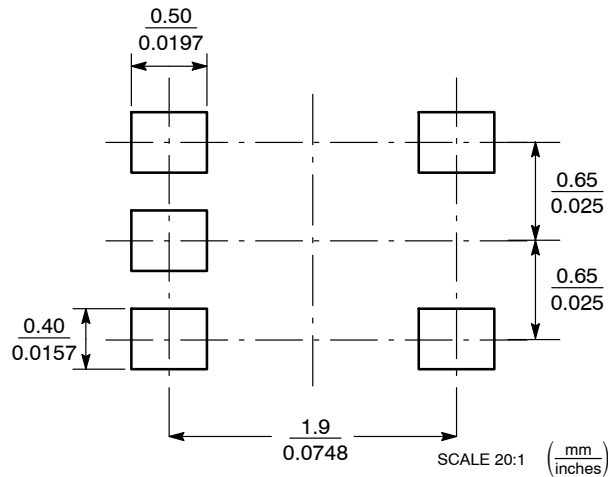


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

SOLDER FOOTPRINT*

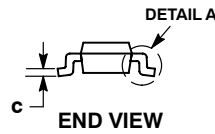
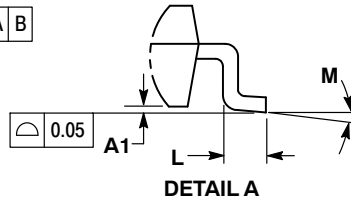
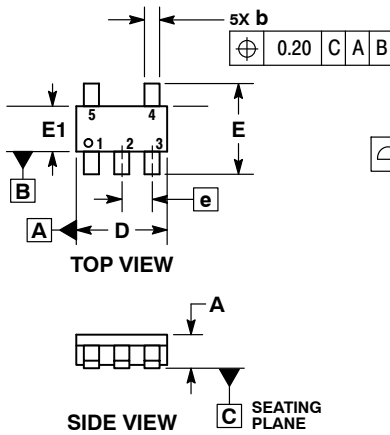


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1GU04

PACKAGE DIMENSIONS

SC-74A CASE 318BQ ISSUE B

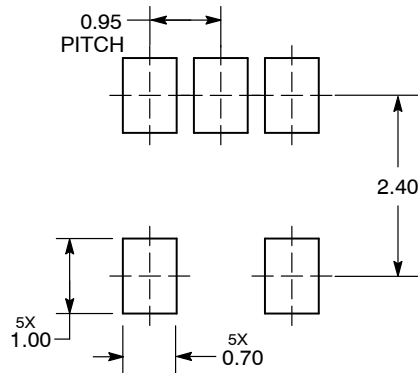


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.10
A1	0.01	0.10
b	0.25	0.50
c	0.10	0.26
D	2.85	3.15
E	2.50	3.00
E1	1.35	1.65
e	0.95 BSC	
L	0.20	0.60
M	0°	10°

RECOMMENDED SOLDERING FOOTPRINT*



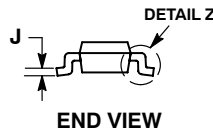
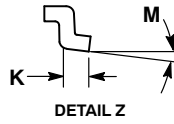
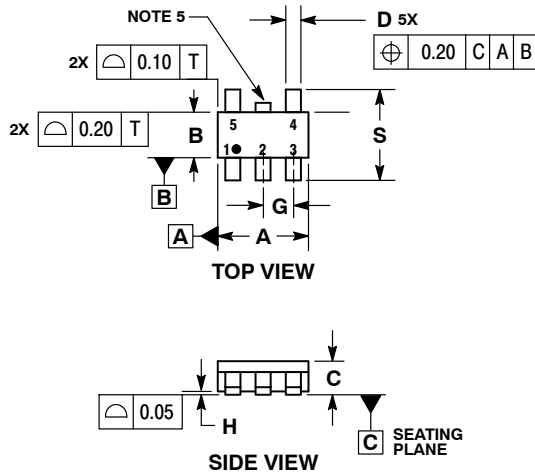
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1GU04

PACKAGE DIMENSIONS

TSOP-5 CASE 483-02 ISSUE N

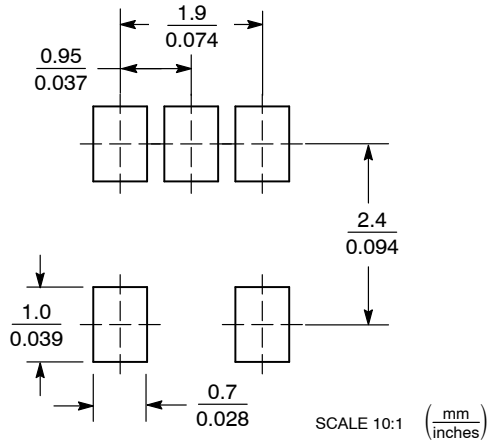


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

DIM	MILLIMETERS	
	MIN	MAX
A	2.85	3.15
B	1.35	1.65
C	0.90	1.10
D	0.25	0.50
G	0.95 BSC	
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
M	0°	10°
S	2.50	3.00

SOLDERING FOOTPRINT*

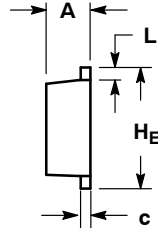
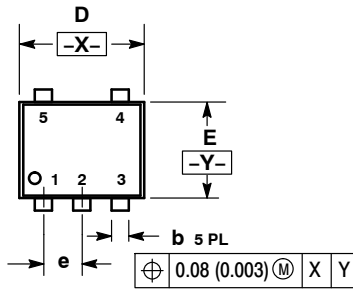


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1GU04

PACKAGE DIMENSIONS

SOT-553, 5 LEAD CASE 463B ISSUE C

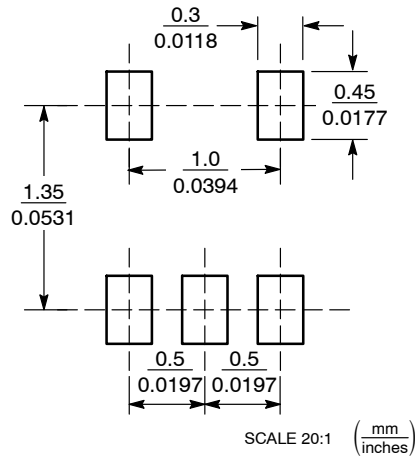


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
c	0.08	0.13	0.18	0.003	0.005	0.007
D	1.55	1.60	1.65	0.061	0.063	0.065
E	1.15	1.20	1.25	0.045	0.047	0.049
e	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	1.55	1.60	1.65	0.061	0.063	0.065

SOLDERING FOOTPRINT*

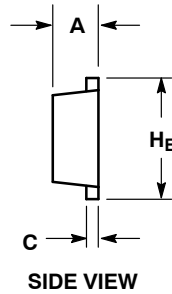
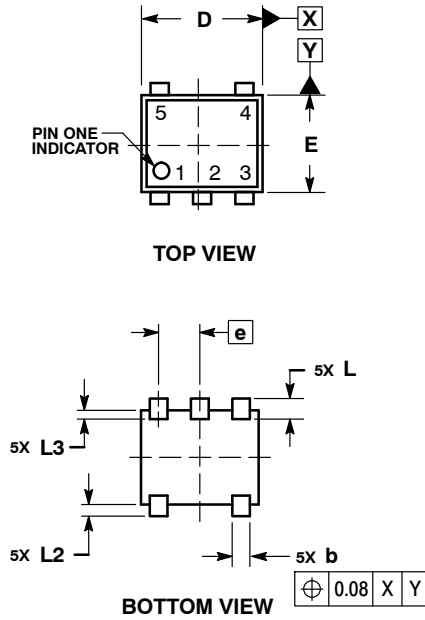


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1GU04

PACKAGE DIMENSIONS

SOT-953
CASE 527AE
ISSUE E

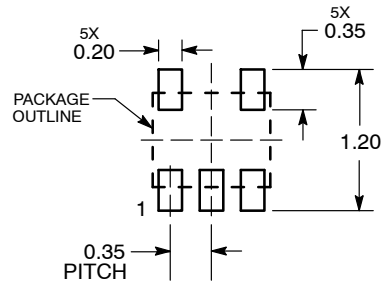


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.34	0.37	0.40
b	0.10	0.15	0.20
C	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
e	0.35 BSC		
H _E	0.95	1.00	1.05
L	0.175 REF		
L2	0.05	0.10	0.15
L3	---	---	0.15

SOLDERING FOOTPRINT*



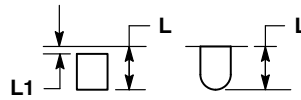
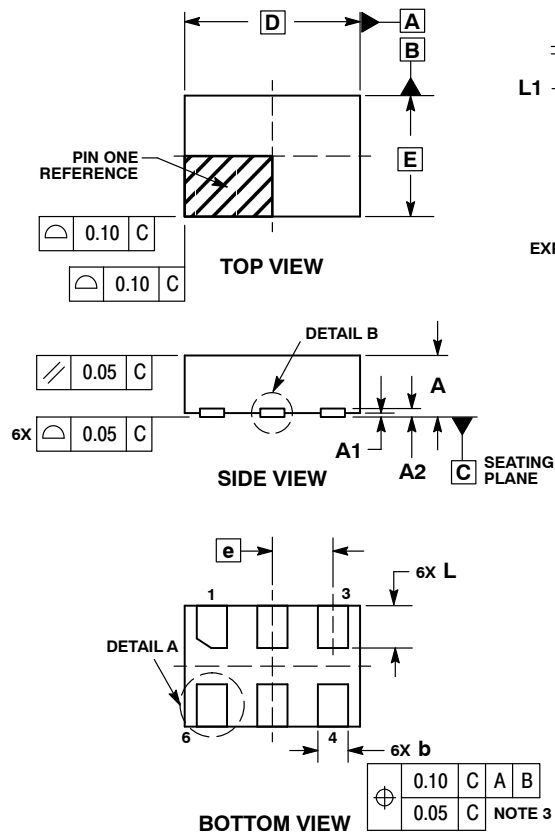
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

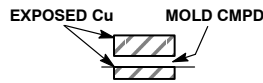
MC74VHC1GU04

PACKAGE DIMENSIONS

UDFN6, 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O



DETAIL A
OPTIONAL
CONSTRUCTIONS



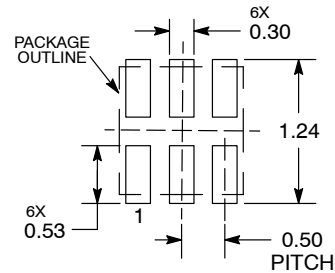
DETAIL B
OPTIONAL
CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07	REF
b	0.20	0.30
D	1.45	BSC
E	1.00	BSC
e	0.50	BSC
L	0.30	0.40
L1	---	0.15

MOUNTING FOOTPRINT



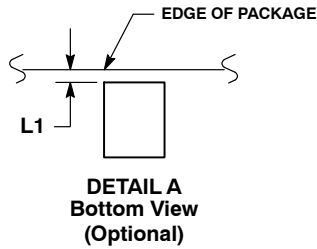
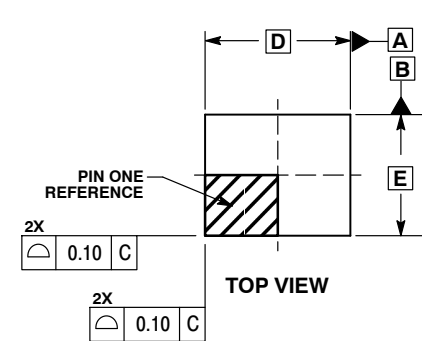
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74VHC1GU04

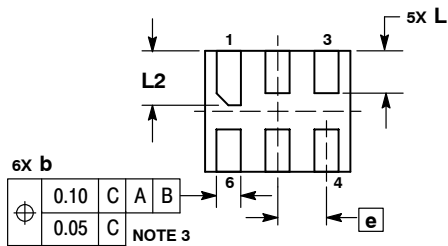
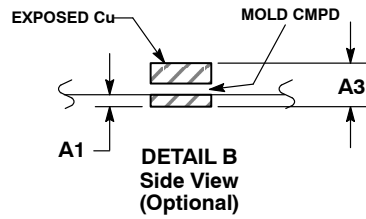
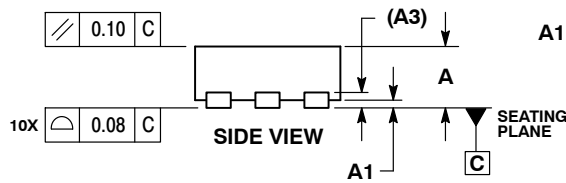
PACKAGE DIMENSIONS

UDFN6, 1.2x1.0, 0.4P
CASE 517AA
ISSUE D

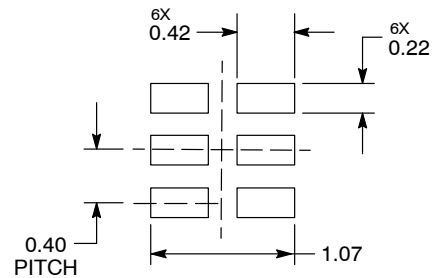


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127	REF
b	0.15	0.25
D	1.20	BSC
E	1.00	BSC
e	0.40	BSC
L	0.30	0.40
L1	0.00	0.15
L2	0.40	0.50



MOUNTING FOOTPRINT*



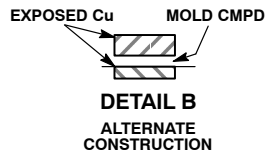
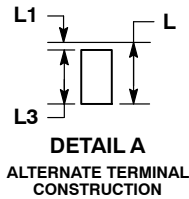
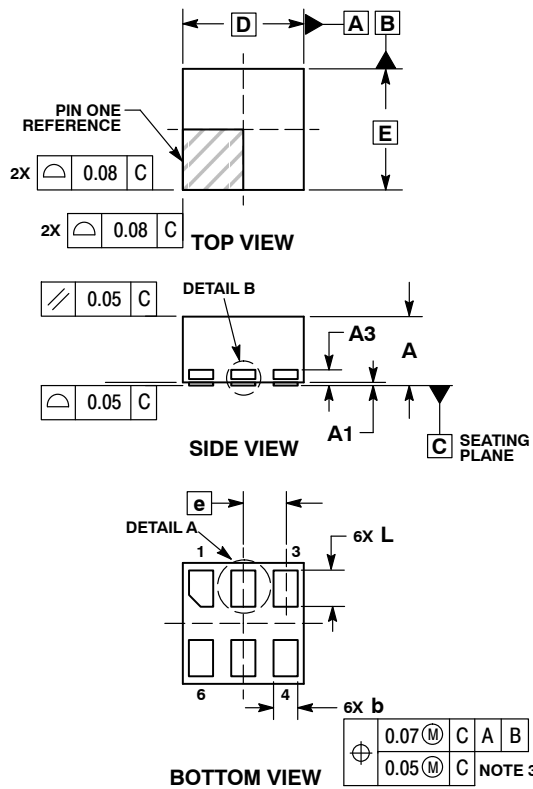
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

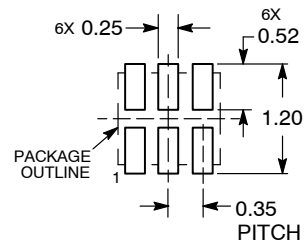
UDFN6, 1x1, 0.35P
CASE 517BX
ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

MILLIMETERS		
DIM	MIN	MAX
A	0.50	0.65
A1	0.00	0.05
A3	0.13 REF	
b	0.17	0.23
D	1.00 BSC	
E	1.00 BSC	
e	0.35	
L	0.20	0.40
L1	---	0.15
L3	0.26	0.33

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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